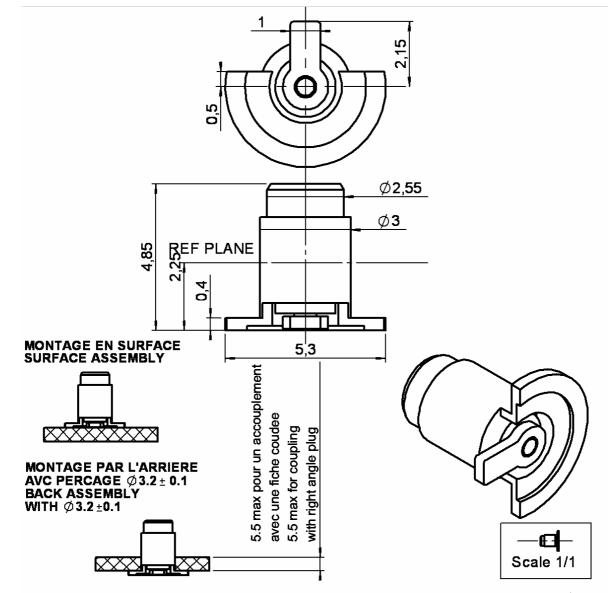
BOBINE DE 100

R199.005.820

Series: MC-CARD



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.5 OVER NICKEL 2 GOLD 1.3 OVER NICKEL2 -
-	-	-

Issue: 0940 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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Series: MC-CARD

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50 Ω

Frequency 0-8 GHz

VSWR 1.15 + 0,0150 x F(GHz) Maxi

Insertion loss $0.07 \ \sqrt{F(GHz)} \ dB \ Maxi$

RF leakage - (- F(GHz)) dB Maxi

Voltage rating 170 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 5000 M Ω mini

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

NA N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 1000 Cycles mini

Weight **0,1600** g

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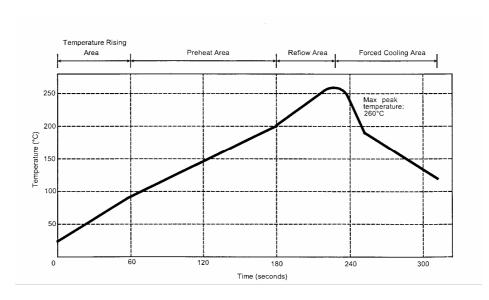
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MC–CARD SERIES – INFORMATIONS SOLDER PROCEDURE OF MC-CARD RECEPTACLES IN INDUSTRIAL ENVIRONMENT

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 - A video camera is recommended for positioning of the component.
 - Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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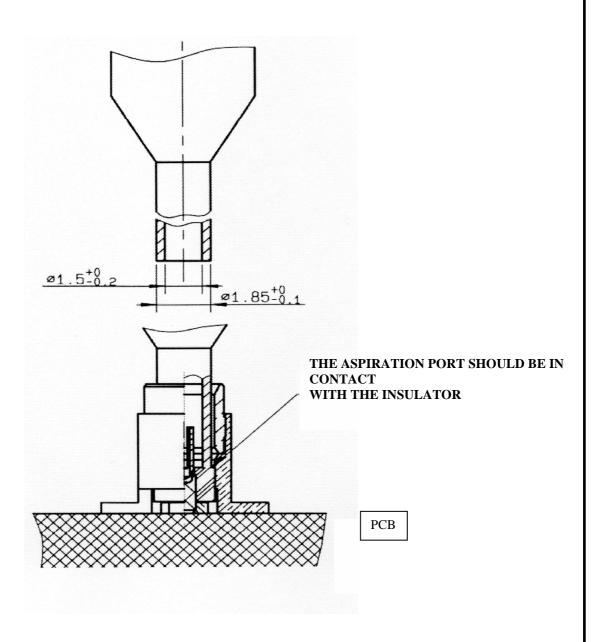
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MC-CARD SERIES - INFORMATIONS

ASPIRATION PORT



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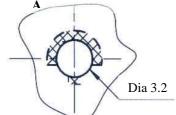
BOBINE DE 100

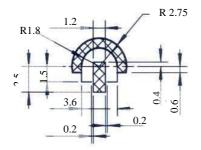
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Series: MC-CARD

MC-CARD SERIES -

SOLUTION









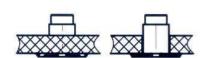
Pattern



Land for solder paste

Receptacle back planting Same printed circuit that B + Dia 0.13

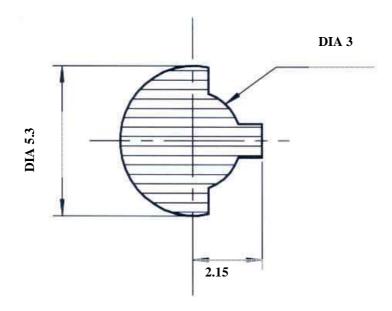
SOLUTION



COPLANAR LINE

Pattern and signal are on the same side Thickness of PCB is the epoxy resin of glass fabric bacs(Er=4.8) The solder resist should be printed exept for the land pattern on the PCB

SHADOW OF MC-CARD RECEPTACLE FOR VIDEO CAMERA



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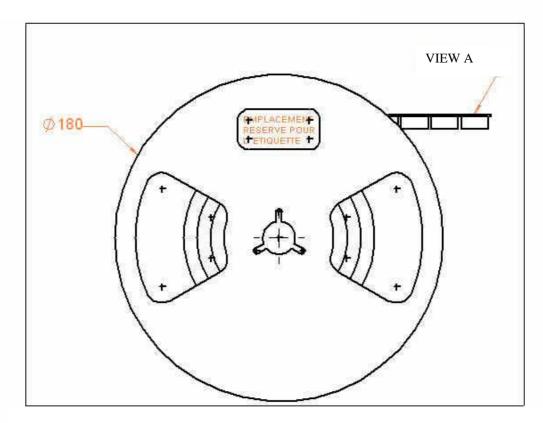


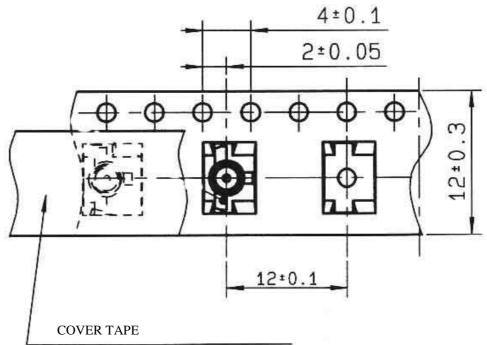
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MC-CARD SERIES INFORMATION





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